

CONDUCTIVE ADHESIVE COMPOSITION

Abstract

A conductive adhesive that does not contain toxic substances such as solder (lead) and shows excellent adhesiveness is provided.

Specifically, it is a conductive adhesive composition, which comprises
(A) a thermosetting resin;
(C) a filler that contains a metal element; and
(D) at least one catalyst or curing agent,
wherein the reaction initiation temperature for the (A) thermosetting resin and the (D) at least one catalyst or curing agent is 180°C or higher.

More preferably, the reaction initiation temperature is 200°C or higher.

More preferably, it is a conductive adhesive composition that further comprises
(B) a flux and (E) a polymer component.

[Figure 1]